ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20303

Generic Copy

Issue Date: 26-Nov-2013

TITLE: Integration of MSOP8 package to Micro8 package

PROPOSED FIRST SHIP DATE: 01-Jul-2014

AFFECTED CHANGE CATEGORY(S): Assembly/Test

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
<Tetsuro.Maruyama@onsemi.com> <Naoki.Koyama@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office
<Takashi.Asami@onsemi.com> <Naoki.Koyama@onsemi.com>

ADDITIONAL RELIABILITY DATA: unavailable
Contact your local ON Semiconductor Sales Office or
<Satoru.Fujinuma@onsemi.com>

NOTIFICATION TYPE:
Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

Kanto Sanyo Semiconductor Factory (located in Japan) will be closed the end of June 2014.
According to Kanto Sanyo Semiconductor Factory closure, MSOP8 package products will be transferred and integrated to MICRO8 package which are currently built in ON Semiconductor SGC Industries Malaysia Sdn Bhd. (SBN).

Current Product Name	Alternative Product Name
LV5113T-TLM-E (MSOP8)	LV5113DMR2G (Micro8)
LV51130T-TLM-E (MSOP8)	LV51130DMR2G (Micro8)
LV51131T-TLM-E (MSOP8)	LV51131DMR2G (Micro8)

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QUALIFICATION PLAN:

Reliability Test was planned as below. Reliability Test Results will be provided in the FPCN.

Test Items	Test Condition	Test Time
Temperature Humidity Bias ※	Ta=85dC, RH=85%, Vcc=Recommended	1000h
Temperature Cycle ※	Ta=-65dC(30min) ⇔ Ta=150dC(30min)	100Cycles
Pressure Cooker ※	Ta=121dC, RH=100%, 205kPa	96h
High Temperature Storage	Ta=150dC	1000h
Resistance to Soldering heat (Reflow soldering)	255dC,10s(Peak260dC)	2times

Notices) The test items with * mark are put into operation after the reflow soldering (at 255C for 10seconds MSL1)
Judgment Criteria : Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

List of affected General Parts:

LV5113T-TLM-E
LV51130T-TLM-E
LV51131T-TLM-E